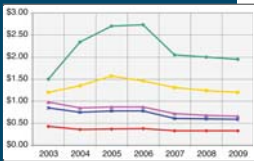


Advanced Packaging Update: Market and Technology Trends

Vol. 2, 2007



The second volume of the Advanced Packaging Update for 2007 features TechSearch International's annual survey on IC package assembly price trends. Packages include QFPs, PBGAs, flip chip PBGAs, QFNs, and laminate CSPs. An analysis of the trends in raw material prices is also provided. The build-up substrate section from the 2007 Japanese JISSO roadmap is summarized. Special coverage of substrate design rules from suppliers of organic flip chip substrates, PBGAs, and laminate CSPs worldwide is provided. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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